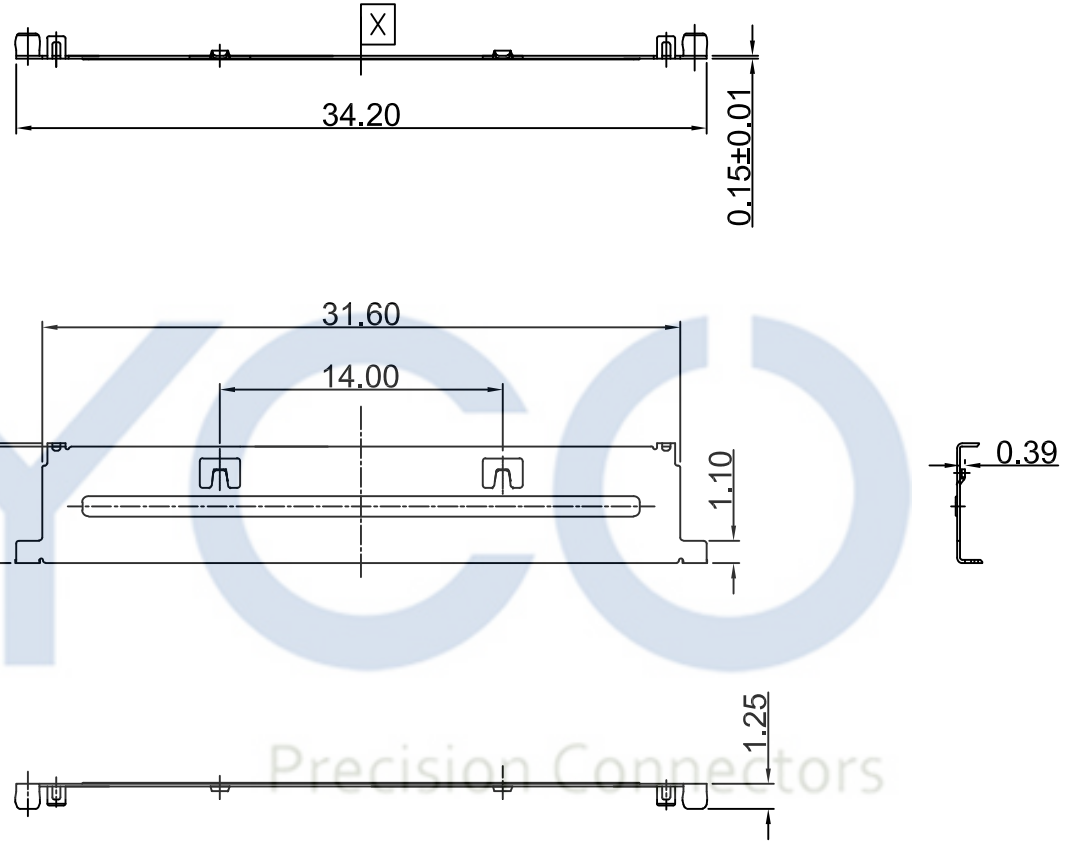
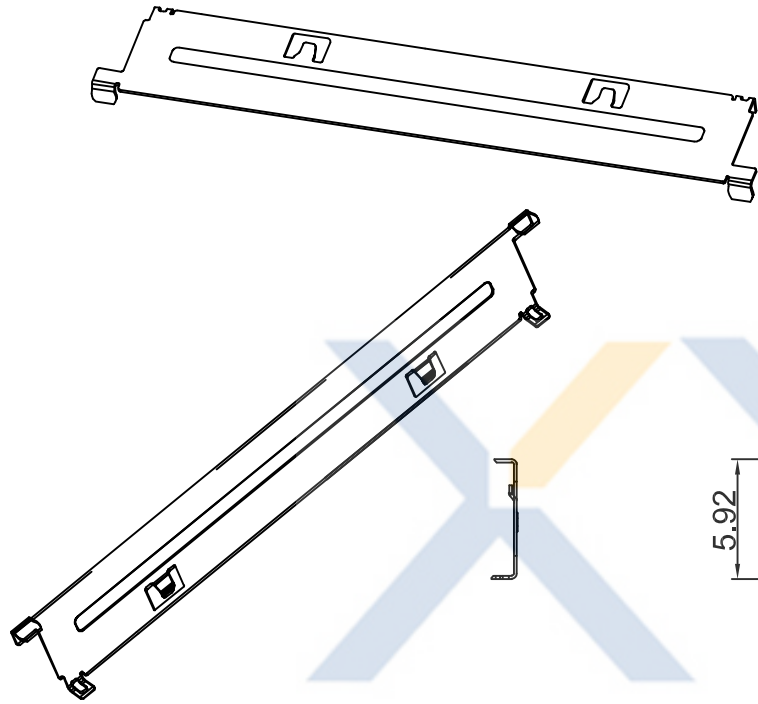


DRAWING FOR CUSTOMER



NOTE

1. MATERIAL: P/B SUS304-H/2,T=0.15±0.01
2. UNLESS OTHERWISE SPECIFIED FORMING R IS R0.05 (INSEIDE R)
3. UNLESS OTHERWISE SPECIFIED BLANK R IS R0.1
4. NO BURR ARE ALLOWABLE ON THE CONTACT AREA,THE MAXIMUM ALLOWABLE STAMPING BURR IS 0.03mm UNLESS OTHERWISE SPECIFIED.
5. THE COPLANARITY OF CONTACTS SHOULD BE LESS THAN 0.05mm BETWEEN ADJACENT PINS.
6. THE CAMBER SHOULD BE LESS THAN 15mm/1000mm AFTER STAMPING PROCESS
7. FINISH:20U" NI UNDERPLATED, 100U" TIN PLATED SOLDER AREA

KB902-30 S S 3 A

Pin No. _____
 Shell _____
 Solder type _____

Version _____
 Mold No. _____

XYCO PRECISION CONNECTORS
 TEL: 0769-8297 9981/2/3 <http://www.XYCO.com.cn>

2016-11-15	A		KB902-30SS3A	John
DATE 日期	VER 版本	CHANGE HISTORY 變更歷史	CHANGED NAME 修改後料號	DRAWING 變更者

TOLERANCE 公差	DRAWING 設計者	John
.X=±0.30	CHECKED 審查	Thomas
.XX=±0.20	APPROVED 核准	William
.XXX=±0.10		

KB902-30SS3A	
PART NO. 料號	
DWG NO. 圖號	PE1709009A

UNIT 單位	mm	PRODUCT NAME 產品名稱	FI-X PH1.00mm Wire To Board Upper shell Solder Type
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